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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/978,420	10/15/2001	Kuo-Yu Chou	67,200-409	5300

7590 06/08/2004  
TUNG & ASSOCIATES  
838 W. Long Lake Road, Suite 120  
Bloomfield Hills, MI 48302

EXAMINER
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RICHARDS, N DREW

ART UNIT	PAPER NUMBER
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2815

DATE MAILED: 06/08/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

Application No.

09/978,420

Applicant(s)

CHOU ET AL.

Examiner

N. Drew Richards

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 18 May 2004.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-3,6 and 13 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-3,6 and 13 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 15 October 2001 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## DETAILED ACTION

### *Claim Rejections - 35 USC § 103*

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1-3, 6 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wang et al. (US 2002/0155672 A1) in view of Koike (U.S. Patent No. 6,392,300 B1).

Wang et al. teach in figures 1-4 and in paragraphs 1-23 a method for fabricating a microelectronic fabrication.

With regard to claim 1, Wang et al. teach a method comprising:

providing a substrate 100 (figure 1);

forming over the substrate a series of patterned conductor layers 102 separated by a series of dielectric layers (figure 1, paragraphs 6-8 and 17); and

forming over the substrate in electrical communication with the series of patterned conductor layers 102 separated by the series of dielectric layers at least one fuse layer 112 (figure 2 shows the fuse layer 112 formed and figures 3 and 4 show the fuse layer after being patterned into fuses 112b and bondpad 112b), wherein the at least one fuse layer 112 is formed at a level no lower than a highest of the series of patterned conductor layers 102 and wherein the at least one fuse layer 112 and the

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highest of the series of patterned conductor layers 102 are formed of different conductor materials.

Wang et al. teach in paragraphs 6-8 the use of fuses to connect normal memory cell arrays and redundant memory cell arrays where the fuse is formed on the uppermost layer of the semiconductor device, the same level as the bond pad. Though the figures show a single patterned conductive layer 102 with fuses over it, it is inherently understood that the semiconductor substrate would include many patterned conductive layers separated by a series of dielectric layer for each memory array and that the fuses would be connected to some of the patterned conductive layers to allow for the fuses to substitute defective memory cells.

Wang et al. do not teach forming the fuse layer simultaneously with an alignment mark.

Koike teach a method of forming a microelectronic fabrication in figures 1-9 and on columns 1-3 for example. Koike teach providing a substrate 11 (figure 1), forming over the substrate a series of patterned conductor layers 18, 21, 24 (figures 2-4) separated by a series of dielectric layers 19, 22 (figures 3 and 4), and forming an alignment mark 27A simultaneously a fuse (not shown) or bond pad 27B (figure 5, column 2 lines 8-11).

Wang et al. and Koike are combinable because they are from the same field of endeavor. At the time of the invention it would have been obvious to a person of ordinary skill in the art to form an alignment mark simultaneously with the fuse layer in an upper metal layer. The motivation for doing so is to provide an alignment mark for

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positioning a laser to allow for blowing of the fuse. Therefore, it would have been obvious to combine Wang et al. with Koike to obtain the invention of claim 1.

With regard to claim 2, Wang et al. teach the microelectronic fabrication selected from integrated circuit microelectronic fabrications, ceramic substrate microelectronic fabrications, solar cell optoelectronic microelectronic fabrications, sensor image array optoelectronic microelectronic fabrications and display image array optoelectronic microelectronic fabrications.

With regard to claim 3, Wang et al. teach the at least one fuse layer is formed simultaneously with a bond pad layer within the microelectronic fabrication in figures 3 and 4 as the same layer 112 is etched to form both the fuse and the bond pad.

With regard to claim 6, the at least one fuse layer is formed of an aluminum containing conductor material and the highest of the series of patterned conductor layers is formed of a copper containing conductor material.

With regard to claim 13, Wang et al. teach a method comprising:

providing a substrate 100 (figure 1);

forming over the substrate a series of patterned conductor layers 102 separated by a series of dielectric layers (figure 1, paragraphs 6-8 and 17); and

forming over the substrate in electrical communication with the series of patterned conductor layers 102 separated by the series of dielectric layers at least one fuse layer 112 (figure 2 shows the fuse layer 112 formed and figures 3 and 4 show the fuse layer after being patterned into fuses 112b and bondpad 112b), wherein the at least one fuse layer 112 is formed at a level no lower than a highest of the series of patterned conductor layers 102 and wherein the at least one fuse layer is formed simultaneously with a bond pad.

Wang et al. teach in paragraphs 6-8 the use of fuses to connect normal memory cell arrays and redundant memory cell arrays where the fuse is formed on the uppermost layer of the semiconductor device, the same level as the bond pad. Though the figures show a single patterned conductive layer 102 with fuses over it, it is inherently understood that the semiconductor substrate would include many patterned conductive layers separated by a series of dielectric layer for each memory array and that the fuses would be connected to some of the patterned conductive layers to allow for the fuses to substitute defective memory cells.

Wang et al. teach the at least one fuse layer is formed simultaneously with a bond pad layer within the microelectronic fabrication in figures 3 and 4 as the same layer 112 is etched to form both the fuse and the bond pad.

Wang et al. do not teach forming the fuse layer simultaneously with an alignment mark.

Koike teach a method of forming a microelectronic fabrication in figures 1-9 and on columns 1-3 for example. Koike teach providing a substrate 11 (figure 1), forming

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over the substrate a series of patterned conductor layers 18, 21, 24 (figures 2-4) separated by a series of dielectric layers 19, 22 (figures 3 and 4), and forming an alignment mark 27A simultaneously a fuse (not shown) or bond pad 27B (figure 5, column 2 lines 8-11).

Wang et al. and Koike are combinable because they are from the same field of endeavor. At the time of the invention it would have been obvious to a person of ordinary skill in the art to form an alignment mark simultaneously with the fuse layer in an upper metal layer. The motivation for doing so is to provide an alignment mark for positioning a laser to allow for blowing of the fuse. Therefore, it would have been obvious to combine Wang et al. with Koike to obtain the invention of claim 13.

### ***Response to Arguments***

3. Applicant's arguments filed 5/18/04 have been fully considered but they are not persuasive.

Applicant argues that their claims (claim 3 and 13) require the simultaneous formation of a bond pad, a fuse layer and an alignment mark but that each of the prior art references teach the simultaneous formation of only two of the three components. Applicant further argues that Koike implicitly teaches that an alignment mark may not be formed when a fuse layer and a bond pad are present. This is not persuasive. First, neither of the two references applied were relied upon to teach the simultaneous formation of all three components, thus the argument that each reference only teaches the simultaneous formation of two components is immaterial. This argument does not

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deal with the fact that the two references were combined to obtain the simultaneous formation of all three components. Second, the fact that Koike teaches simultaneously forming an alignment mark with either a fuse layer or a bond pad does not imply that all three can not be formed together. There is nothing in the Koike reference that would lead one to believe that all three cannot be formed together. Just because Koike only teaches two of them does not prove that all three cannot be formed. Koike is not considered to teach away from the combination as nothing in their disclosure prohibits or prevents all three components being formed together.

Applicant also argues that Wang and Koike may not be properly combined since their mere existence in the same field of endeavor provides an insufficient basis to establish prima facie obviousness. This argument is not persuasive. The Examiner has provided sufficient basis to establish prima facie obviousness. The references are properly combinable as the suggestion or motivation for the combination has been stated in the rejection.

Applicant also argues that the motivation for combination is applicable to a specific situation taught within Koike and is not necessarily applicable to Wang. This argument is not persuasive as Wang recognize a need to have the ability to blow their fuses. Koike teach forming an alignment mark that is used for alignment to locate the fuses for blowing the fuses. The motivation is thus considered applicable to Wang in



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order to allow for the blowing of fuses, such blowing the fuses recognized as Wang as useful to replace defective memory cells.

Applicant also argues that although Koike teach an alignment mark formed simultaneously with a fuse layer, an alignment mark formed at an alternative level within a microelectronic component would also be operational for purposes of alignment when severing the fuse. This argument is not relevant as Koike do not teach the alignment mark on an alternative level but teach the alignment mark on the same level as, and formed simultaneously, with the fuse layer.

Applicant's argues that had Wang simultaneously formed an alignment mark, the same would also have clearly been exposed for proper alignment purposes. This is not persuasive as it is not relevant to the rejection as applied. If Wang did teach the simultaneous formation of the alignment mark the claims would have been rejected under 35 U.S.C. 102 as anticipated by Wang.

### ***Conclusion***

4. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

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A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to N. Drew Richards whose telephone number is (571) 272-1736. The examiner can normally be reached on M-F 8:00-5:30; Every other Friday off.

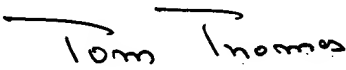
If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



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